

PATENT
81790.0189

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

MOMOHARA, Tomomi

Serial No: 09/686,200 (reissue of 08/718,660)

Filed: October 5, 2000

For: PROBE CARD HAVING GROUPS
OF PROBE NEEDLES IN A
PROBING TEST APPARATUS FOR
TESTING SEMICONDUCTOR
INTEGRATED CIRCUITSAMENDMENTCommissioner for Patents
Washington, D.C. 20231

Art Unit: 2829

Examiner: NGUYEN, Vinh P.

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to:

Commissioner for Patents
Washington D.C. 20231, on

April 10, 2003
Date of Deposit

Michael Crapenhoft, Reg. No. 37.115
Name

Michael Crapenhoft April 10, 2003
Signature Date

Dear Sir:

In response to the Office Action dated October 10, 2002, the time for response to which is extended three months by the accompanying petition from January 10, 2003 to April 10, 2003, please amend the above-referenced reissue application as follows:

FAX RECEIVED

IN THE CLAIMS:

6-12

Please replace the text of claims 6-11 with the following amended text:

APR 10 2003

TECHNOLOGY CENTER 2800

6. (Amended) A method for testing semiconductor integrated circuits, the method comprising:

providing a semiconductor wafer having a plurality of semiconductor integrated circuit chips arranged thereon in two columns and at least two rows, each of said plurality of semiconductor integrated chips having a plurality of external terminals;